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**REPLY UNDER 37 CFR §1.116**  
**EXPEDITED PROCEDURE**  
**TECHNOLOGY CENTER 2800**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:  
William Hong, et al.

Serial No.: 10/714,985

Filed: November 17, 2003

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Group Art Unit: 2813

Examiner: Thanh T. Nguyen

Confirmation No.: 2268

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Sir:

I hereby certify that this correspondence (including any listed enclosures) is being facsimile transmitted (703-872-9306) to the United States Patent and Trademark Office on April 11, 2005.  
*Kelly A. Moreau*  
Kelly A. Moreau

**RESPONSE UNDER 37 CFR §1.116**

This Response is submitted in reply to the Office Action mailed on February 2, 2005.  
(Please see the pages that follow).